



Integrated Device Technology, Inc.
6024 Silver Creek Valley Road, San Jose, CA - 95138

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: **N1309-01** DATE: **October 1, 2013**

Product Affected: 841N254AKILF, 841N254AKILFT

Date Effective: **January 1, 2014**

MEANS OF DISTINGUISHING CHANGED DEVICES:

- Product Mark Change of Orderable Part#. Refer to Attachment I.
- Back Mark
- Date Code
- Other

Contact: TSD Clock Team

Attachment: Yes No

E-mail: clocks@idt.com

Samples: Contact your local sales representative for sample and datasheet requests.

DESCRIPTION AND PURPOSE OF CHANGE:

- Die Technology
- Wafer Fabrication Process
- Assembly Process
- Equipment
- Material
- Testing
- Manufacturing Site
- Data Sheet
- Other - Die Revision

This notification is to advise our customers of a silicon die revision. The current die revision A will be changed to revision B.

IDT requests customers to use "B" revision in their newer design/projects and switch existing design/projects to "B" revision as soon as possible. Last time buy for revision A will be on 1/1/2014.

RELIABILITY/QUALIFICATION SUMMARY:

Characterization tests will verify that there is no change to the performance or reliability of the product.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.

IDT reserves the right to ship either version manufactured after the process change effective date.

Customer: _____

Approval for shipments prior to effective date.

Name/Date: _____

E-Mail Address: _____

Title: _____

Phone# /Fax# : _____

CUSTOMER COMMENTS: _____

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: _____

DATE: _____



PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT I - PCN # : N1309-01

PCN Type: Die Revision

Data Sheet Change: No

Details Of Change:

This notification is to advise our customers of a silicon die revision. The current die revision A will be changed to revision B.

IDT requests customers to use "B" revision in their newer design/projects and switch existing design/projects to "B" revision as soon as possible. Last time buy for revision A will be on 1/1/2014.

Revision B has the following improvements and design enhancements/features:

- 1) Replaced the crystal input structure, xtal_pierce03, with xtal_pierce04.
- 2) Repositioned an internal buffer to result in more robust re-timing.

There will be a change in ordering part number. Refer to Table 1.

There is no change to thermal and MSL specification due to this die revision.

There is no change to device process or technology.

Table 1: Ordering Part# Changes

Old Ordering Part Number	New Ordering Part Number
841N254AKILF	841N254BKILF
841N254AKILFT	841N254BKILFT